

MATERIAL DECLARATION SHEET



Material Number	PTVS10-058C-SH			
Product Line	Semiconductor products			
Compliance Date	April 2 nd 2014			
RoHS Compliant	Yes	MSL	Level 1	

No.	Construction Element (subpart)	Homogenous Material	Material Weight (g)	Homogenous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart Mass % of total unit wt.	Material Weight (g)
1	Encapsulation	Epoxy Resin	0.522736	Bisphenol Epoxy Resin	1675-54-3	40.00	5.60	13.99	0.209
				Epoxy Resin	25085-99-8	20.00	2.80		0.105
				Crystalline Silica	14464-46-1	23.00	3.22		0.120
				Brominated Epoxy Resin	40039-93-8	12.00	1.68		0.063
				Iron Oxide	51274-00-1	2.00	0.28		0.010
				Titanium Oxide	13463-67-7	3.00	0.42		0.016
2	Electrodes	Copper	1.781057	Copper	7440-50-8	99.10	47.25	47.68	1.765
				Silver	7440-22-4	0.40	0.19		0.007
				Misc not to declare	-	0.50	0.24		0.009
3	Terminations	Copper	1.079704	Copper	7440-50-8	99.50	28.76	28.90	1.074
				Misc not to declare	-	0.50	0.14		0.005
4	Termination Finish	Silver	0.015286	Silver	7440-22-4	100.00	0.41	0.41	0.015
5	Chip	Silicon Die	0.147247	Silicon	7440-21-3	85.74	3.38	3.94	0.126
				Aluminium	7429-90-5	4.99	0.20		0.007
				Nickel	7440-02-0	8.84	0.35		0.013
				Gold	7440-57-5	0.43	0.02		0.001
6	Die Attach	Solder	0.111586	Lead	7439-92-1	92.50	2.76	2.99	0.103
				Tin	7440-31-5	5.00	0.15		0.006
				Silver	7440-22-4	2.50	0.07		0.003
7	Die Coating	Silicone	0.078174	Polysiloxane	63148-62-9	22.11	0.46	2.09	0.017
				Chromium Sesquioxide	1308-38-9	5.67	0.12		0.004
				Fumed Silica	112945-52-5	11.11	0.23		0.009
				Filler	trade secret	61.11	1.28		0.048
Total Weight			3.735789						